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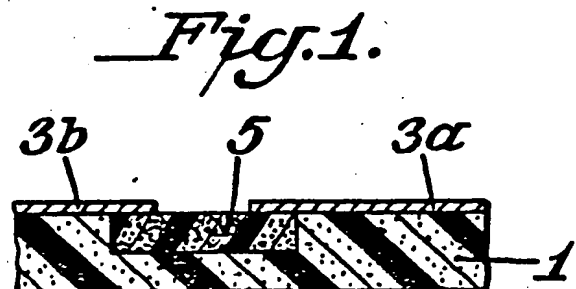
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54 A printed circuit substrate.

57 A printed circuit is provided wherein electrically conductive material (5) which forms part of the circuit elements is embedded within a dielectric substrate (1). The preferred dielectric substrate is porous, expanded polytetrafluoroethylene.



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A PRINTED CIRCUIT SUBSTRATE

This invention relates to printed circuits comprising a substrate and electrical circuit elements. Conventional circuits of this type include, for example, the substrate shown in Figure 4 of the accompanying drawings. Figure 4 is a cross-sectional view of one portion of a printed circuit substrate on which electrical circuits are formed.

Specifically, openings 2a,2b are formed at prescribed positions in the printed circuit substrate 1, and a conductor 3, such as a copper foil, is printed on to the top and bottom surfaces of the printed circuit substrate 1 and interior surfaces of the holes 2a,2b in accordance with the circuit wiring pattern as shown. This conductor 3 is formed by a well known printed wiring technique such as, for example, etching and plating.

Furthermore, as shown in figure 4, a resistor 4 is connected to the printed circuit substrate 1 by lead wires 4a,4b which are soldered into the openings 2a,2b. This resistor 4 forms a part of one of the electrical circuits.

In the abovementioned conventional circuitry, electrical circuits are formed by attaching circuit elements such as the resistor 4 to the surface of the printed circuit substrate 1 after the aforementioned conductor 3 has been printed on to the substrate. As a result, unnecessary irregularities can be created on the surface of the printed circuit board. Furthermore, there is a possibility that the printed circuit substrate 1 will be damaged by the heat generated by the soldering of the lead wires. Moreover, in cases where soldering is insufficient, unsatisfactory electrical connections may result.

The present invention was conceived in light of the abovementioned problems encountered in conventional circuitry.

According to the present invention there is provided a printed circuit comprising conductive material which forms circuit elements embedded within a dielectric substrate.

The conductive material may be a low-conductivity material which forms a resistor or a high-dielectric constant material which forms a capacitor. The conductive material may be a material having high magnet permeability. The dielectric substrate preferably is a porous dielectric material, more preferably a continuously porous dielectric material and most preferably porous, expanded polytetrafluoroethylene. The conductive material may be electrically conductive or light conducting. The conductive material may be impregnated within the dielectric substrate.

Embodiments of the invention will now be particularly described, by way of example, with refer-

ence to the accompanying drawings in which:-

Figure 1 is a cross-sectional view of one embodiment of the printed circuit according to the present invention;

Figure 2 is a cross-sectional view of another embodiment wherein conductive material forms a capacitor in the printed circuit;

Figure 3 is a cross-sectional view of a still further embodiment wherein a material having high magnetic permeability is embedded within the dielectric substrate, and

Figure 4 is a cross-sectional view of a known printed circuit.

A printed circuit is provided wherein the electrically conductive material which forms the circuit elements is embedded within a dielectric substrate. The preferred dielectric substrate is porous, expanded polytetrafluoroethylene.

Specifically, in the printed circuit substrate of the present invention, materials which form circuit elements are contained inside a dielectric substrate. The term "printed circuit substrate" is used herein as a general term for substrates used for the printed wiring of electrical circuits and optical circuits, and includes, for example, substrates which are generally referred to as printed wiring boards, printed circuit boards or printed wiring substrates.

Since required circuit elements are contained inside the substrate, no unnecessary irregularities are created on the surface of the printed circuit substrate. Furthermore, since there is no need to attach circuit elements after assembly, unsatisfactory electrical connections due to faulty soldering are minimized. Moreover, desired circuits can be formed merely by laminating a multiple number of substrates together.

Figure 1 illustrates one example of the present invention. Specifically, printed circuit substrate 1 contains a low-conductivity material 5, such as polytetrafluoroethylene filled with carbon black, that forms a resistor in an electrical circuit. This material 5 is contained so that it is partially exposed at the surface of the substrate 1. Conductors 3a,3b, consisting of copper foil, are printed on the surface of the printed circuit substrate 1 so that the conductors separately contact the aforementioned low-conductivity material 5. These conductors 3a,3b are printed by a well known wiring technique such as etching or plating in the same manner as in the abovementioned conventional technology.

The dielectric which makes up the printed circuit substrate 1 is preferably formed from expanded, porous polytetrafluoroethylene, which is continuously porous material, and the printed circuit

substrate 1 can be impregnated with the low-conductivity material 5, so that this material is contained inside the pores of the substrate. Furthermore, the impregnation of the substrate with the abovementioned low-conductivity material 5 can be promoted by pre-impregnating the target region, where the low-conductivity material 5 is to be installed, with a solvent used for substitution purposes. The low-conductivity material 5 thereby forms a resistor, and the conductors 3a,3b form lead wires, thereby completing one portion of an electrical circuit according to the invention.

As a result of this construction, no unnecessary irregularities are formed on the surface of the printed circuit substrate 1. Accordingly, a multilayer printed circuit board can easily be formed. Furthermore, since there are no connections depending on weak lead wires or soldered connections of relatively low durability, there is less of a tendency for the circuit board to be damaged by external shocks and vibrations. Furthermore, the printed circuit board is not damaged by the heat of soldering, and unsatisfactory electrical connections due to faulty soldering are eliminated.

Figure 2 illustrates a second example of the present invention. In this example, a high-dielectric constant material 6, such as polytetrafluoroethylene tape filled with TiO_2 or BaTiO_3 powder, which forms a capacitor, is contained in the printed circuit substrate 1 so that said material 6 is exposed at the top and bottom surfaces of the printed circuit substrate 1. Conductors 3a,3b are printed by the same method as in the aforementioned first example, so that these conductors separately contact the top and bottom surfaces of the high-dielectric constant material 6. The structure and effects are substantially the same as in the aforementioned first example.

Figure 3 illustrates a third example of the present invention. In this example, a high-magnetic-permeable material 7, such as polytetrafluoroethylene tape filled with molybdenum permalloy powder, is contained inside the printed circuit substrate 1, and conductors 3a, 3b are wired parallel to each other on the surface of the printed circuit substrate 1.

The lines of magnetic force generated when a current flows through conductor 3a, indicated by the dashed lines in Figure 3, tend not to reach conductor 3b as a result of the shielding effect of the high-magnetic-permeable material 7. As a result, almost no current flows through conductor 3b. Furthermore, a similar effect is also obtained when a current flows through conductor 3b. The remaining structure and effects are substantially the same as in the aforementioned first example of application.

In the abovementioned examples, the material

used to form the printed circuit substrate was expanded, porous polytetrafluoroethylene. However, the material used for the substrate is not limited to this material. For example, a porous dielectric such as porous polyester could also be used.

Circuit elements which are attached after assembly as in conventional circuitry can be utilized together with the present invention. In addition, materials for optical circuits can also be contained inside the printed circuit substrate.

Examples of circuit formation using a single substrate 1 were described above. However, it would also be possible to form circuits on substrates installed above or below the abovementioned substrate of the present invention, or jointly with substrates installed above and/or below the above-mentioned substrate of the present invention.

Claims

1. A printed circuit comprising conductive material which forms circuit elements embedded within a dielectric substrate.

2. A printed circuit according to claim 1 wherein said conductive material is a low-conductivity material which forms a resistor.

3. A printed circuit according to claim 1 wherein said conductive material is a high-dielectric constant material which forms a capacitor.

4. A printed circuit according to claim 1 wherein said conductive material is a material having high magnetic permeability.

5. A printed circuit according to claim 1 wherein said dielectric substrate is a porous dielectric material.

6. A printed circuit according to claim 5 wherein said dielectric substrate is a continuously porous dielectric material.

7. A printed circuit according to claim 6 wherein said dielectric substrate is porous, expanded polytetrafluoroethylene.

8. A printed circuit according to claim 1 wherein said conductive material is electrically conductive.

9. A printed circuit according to claim 1 wherein said conductive material is light conducting.

10. A printed circuit according to claim 1 wherein said conductive material is impregnated within said dielectric substrate.

Fig. 1.

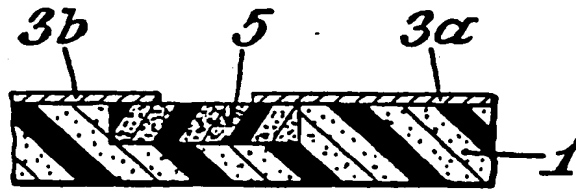


Fig. 2.

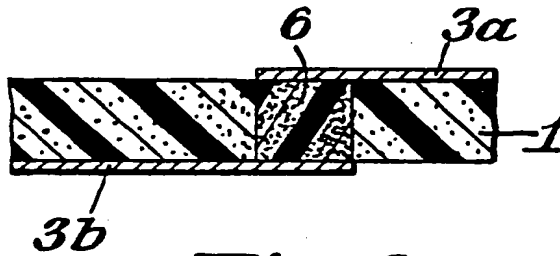


Fig. 3.

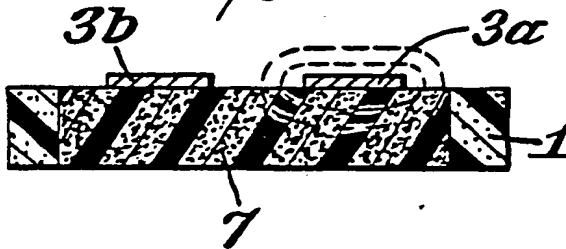
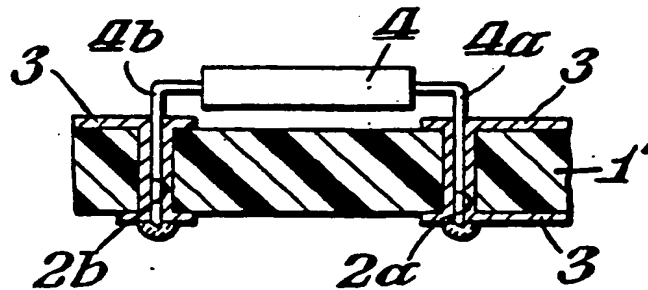


Fig. 4.



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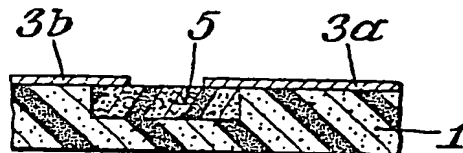
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Fig. 1.



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European Patent
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EUROPEAN SEARCH REPORT

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DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl. 4)
X	IBM TECHNICAL DISCLOSURE BULLETIN, vol. 20, no. 9, February 1978, pages 3436-3437, New York, US; R.O. LUSSOW: "Internal capacitors and resistors for multilayer ceramic modules" * Page 3437, lines 8-17; figure 4 *	1-3,8	H 05 K 1/03 H 05 K 1/16 H 01 C 7/00
A	Idem	10	
P,A	EP-A-0 248 617 (JAPAN GORE-TEX. INC.) * Page 7, lines 1-13; page 9, lines 1-8,20-24 *	5-7,10	
A	FR-A-1 117 524 (J.G.H.E. MICHEL) * Page 1, column 2, lines 1-15; page 2, lines 10-90 *	1-4,8	
A	GB-A- 923 842 (MORGANITI RESISTORS LTD) * Page 1, lines 14-32; claims 1,6,8,10 *	1,2,5-8,10	
P,X	WO-A-8 806 064 (LOCKHEED CORP.) * Page 3, lines 1-6; page 5, lines 1-9; page 12, lines 4-31 *	1-6,8	
			TECHNICAL FIELDS SEARCHED (Int. Cl.4)
			H 05 K H 01 C
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 28-06-1989	Examiner MOMENE Y ARROYO M.E.
CATEGORY OF CITED DOCUMENTS			
X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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